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(12) **United States Design Patent**  
**Igarashi et al.**

(10) **Patent No.:** **US D661,262 S**  
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(54) **LIGHT EMITTING DIODE**

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(73) Assignee: **Nichia Corporation** (JP)

(\*\*) Term: **14 Years**

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Oct. 26, 2009	(JP)	.....	2009-024959
Oct. 26, 2009	(JP)	.....	2009-024960
Oct. 26, 2009	(JP)	.....	2009-024961

(51) **LOC (9) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/180**

(58) **Field of Classification Search** ..... D13/180;  
D26/1, 2; 257/79, 80, 81, 88, 89, 95, 98,  
257/99, 100, E33.058; 313/483, 498, 500;  
362/555, 800

See application file for complete search history.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

D439,351 S *	3/2001	Kiba et al.	.....	D26/37
6,483,623 B1 *	11/2002	Maruyama	.....	398/182

(Continued)

**FOREIGN PATENT DOCUMENTS**

JP 2000-183405 6/2000

(Continued)

**OTHER PUBLICATIONS**

2009 Nichia LED Catalogue, Mar. 2009, pp. 56, 57, 98, 99 (<http://www.nichia.co.jp>).

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(57) **CLAIM**

The ornamental design for a light emitting diode, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top, right side perspective view of a first embodiment of a light emitting diode showing our new design;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a rear elevational view thereof;

FIG. 4 is a top plan view thereof;

FIG. 5 a bottom plan view thereof;

FIG. 6 is a right side elevational view thereof;

FIG. 7 a left side elevational view thereof;

FIG. 8 is a front, top, right side perspective view of a second embodiment thereof;

FIG. 9 is a front elevational view thereof;

FIG. 10 is a rear elevational view thereof;

FIG. 11 is a top plan view thereof;

FIG. 12 is a bottom plan view thereof;

FIG. 13 is a right side elevational view thereof;

FIG. 14 is a left side elevational view thereof;

FIG. 15 is a front, top, right side perspective view of a third embodiment thereof;

FIG. 16 is a front elevational view thereof;

FIG. 17 is a rear elevational view thereof;

FIG. 18 is a top plan view thereof;

FIG. 19 is a bottom plan view thereof;

FIG. 20 is a right side elevational view thereof; and,

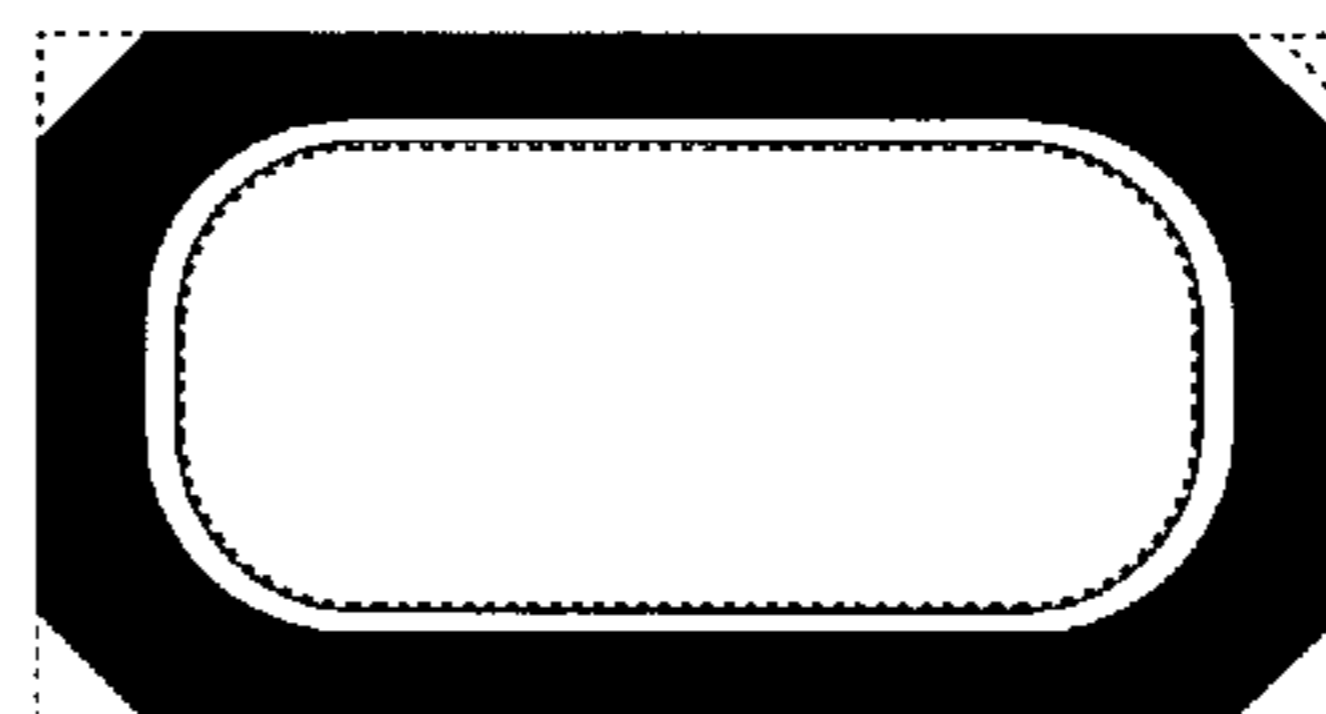
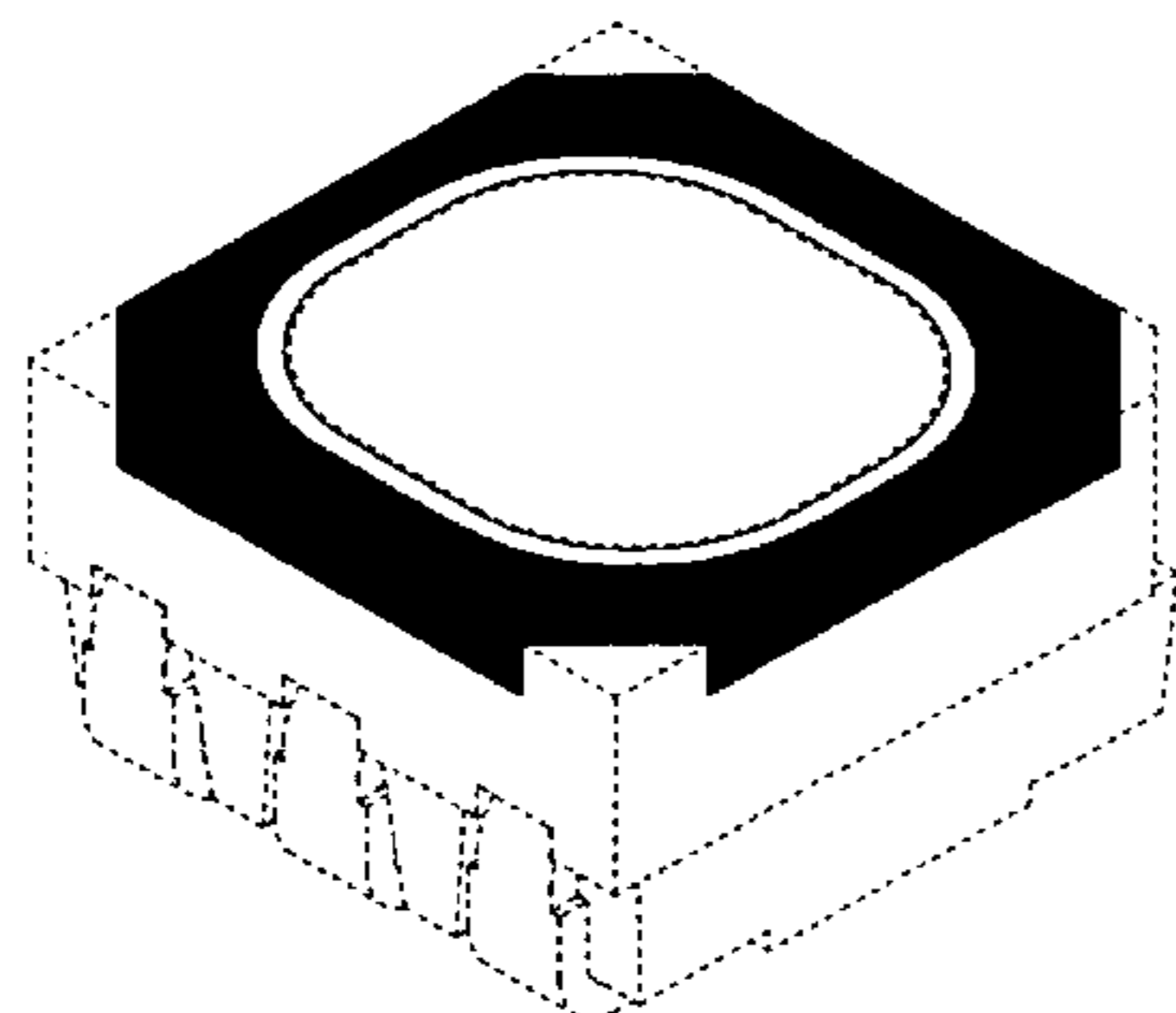
FIG. 21 is a left side elevational view thereof.

The portions shown in black indicate the color black. The thin rectangular, square and oval portions surrounding the center top unclaimed windows in FIGS. 1, 4, 8, 11, 15 and 18, indicate the color white.

The thin white portions of all embodiments are substantially planar and flush with the surrounding black body portions.

The broken lines are for the purpose of illustrating portions of the light emitting diode and form no part of the claimed design. The unshaded window portions inside the broken lines that are adjacent the thin, white rectangular, square and oval portions in FIGS. 1, 4, 8, 11, 15 and 18 are not part of the claimed design.

**1 Claim, 3 Drawing Sheets**



# US D661,262 S

Page 2

## U.S. PATENT DOCUMENTS

D471,166 S \* 3/2003 Oshio et al. .... D13/182  
6,707,069 B2 \* 3/2004 Song et al. .... 257/79  
D491,899 S \* 6/2004 Yagi ..... D13/180  
D494,550 S 8/2004 Hoshiba  
D495,304 S \* 8/2004 Kim et al. .... D13/180  
D505,396 S \* 5/2005 Hoshiba ..... D13/180  
D511,329 S \* 11/2005 Suenaga ..... D13/180  
D522,468 S \* 6/2006 Song ..... D13/180  
D535,263 S \* 1/2007 Sumitani ..... D13/180  
D578,083 S \* 10/2008 Shimonishi et al. .... D13/180  
D584,246 S \* 1/2009 Low et al. .... D13/180  
D586,302 S \* 2/2009 Kim et al. .... D13/180

D608,309 S \* 1/2010 Kim ..... D13/180  
D608,740 S \* 1/2010 Lu et al. .... D13/180  
D611,012 S \* 3/2010 Hsieh ..... D13/180  
D621,800 S \* 8/2010 Hsieh ..... D13/180  
D621,801 S \* 8/2010 Hsieh ..... D13/180  
D622,682 S \* 8/2010 Park et al. .... D13/180  
7,815,343 B2 \* 10/2010 Nii et al. .... 362/311.03  
D627,312 S \* 11/2010 Lai et al. .... D13/180

## FOREIGN PATENT DOCUMENTS

JP 2006-130714 5/2006

\* cited by examiner

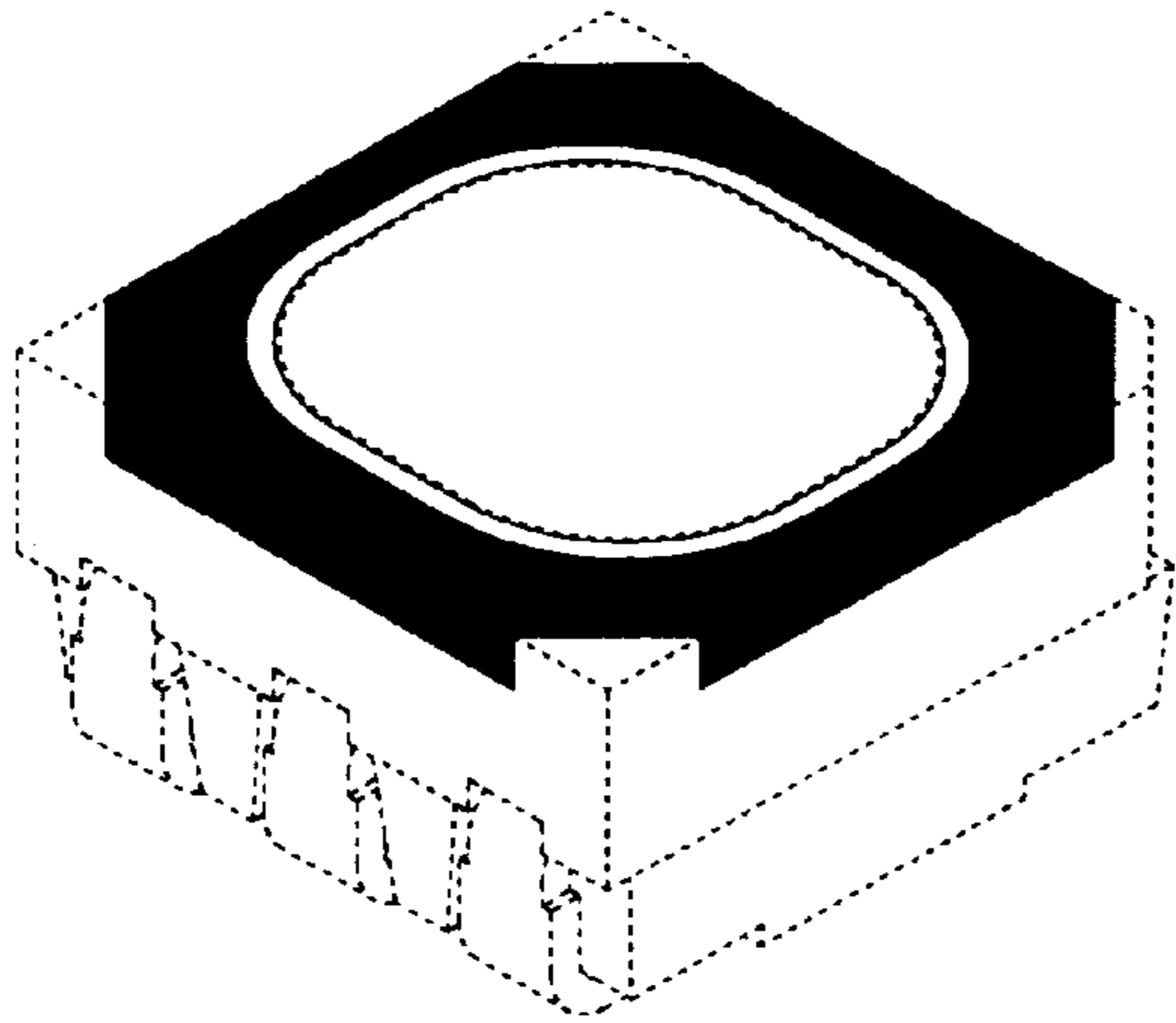


FIG. 1

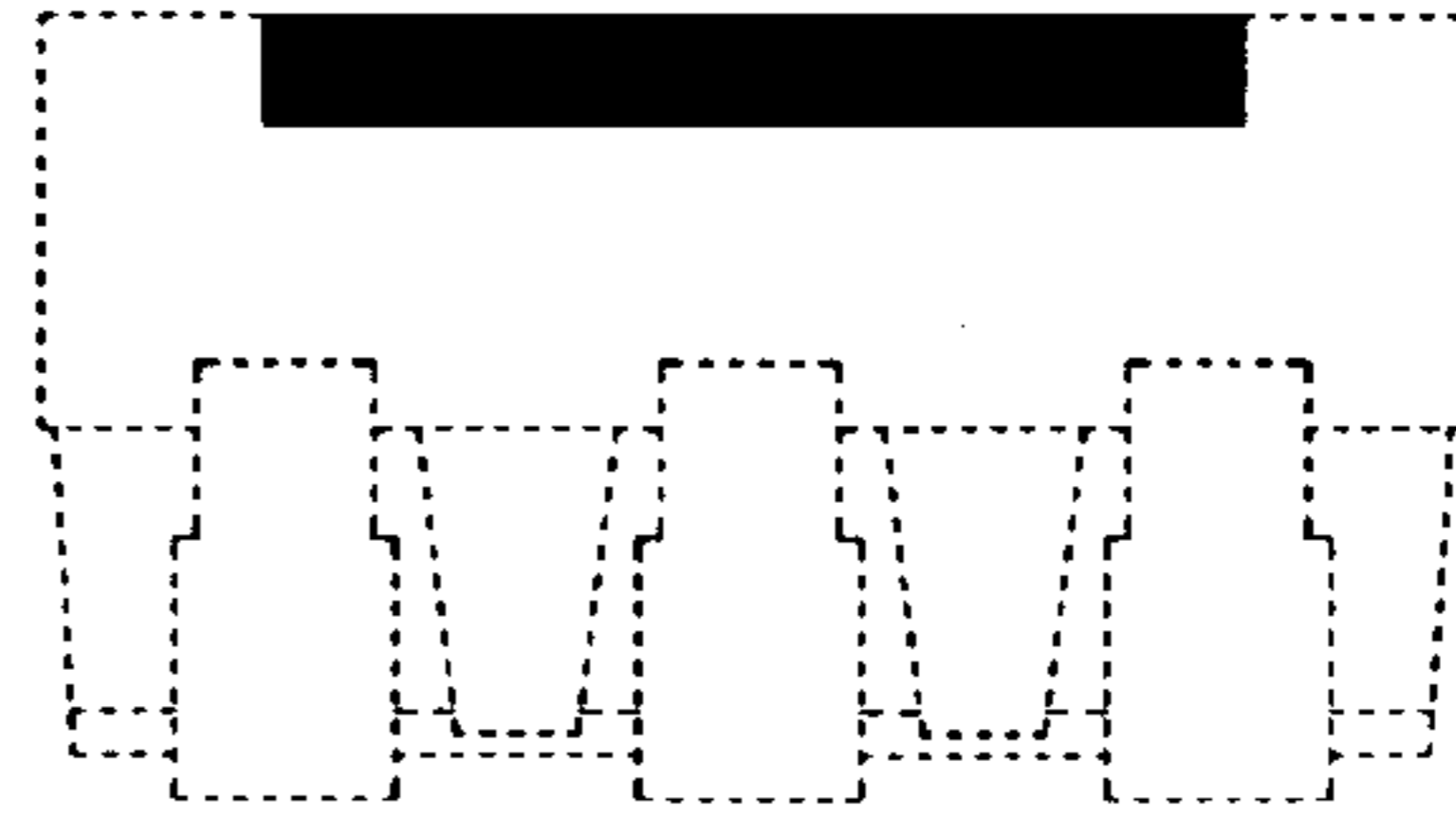


FIG. 2

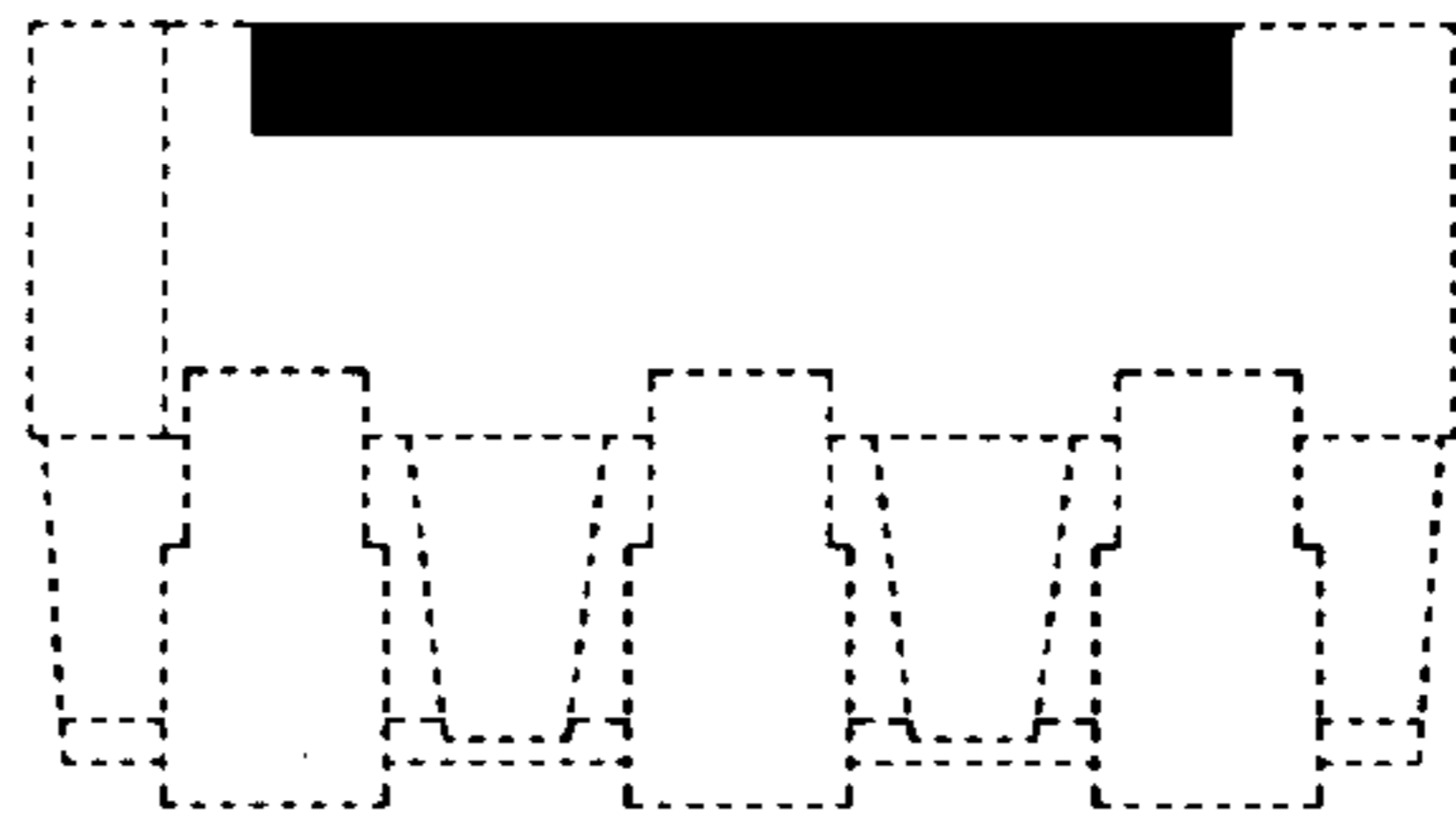


FIG. 3

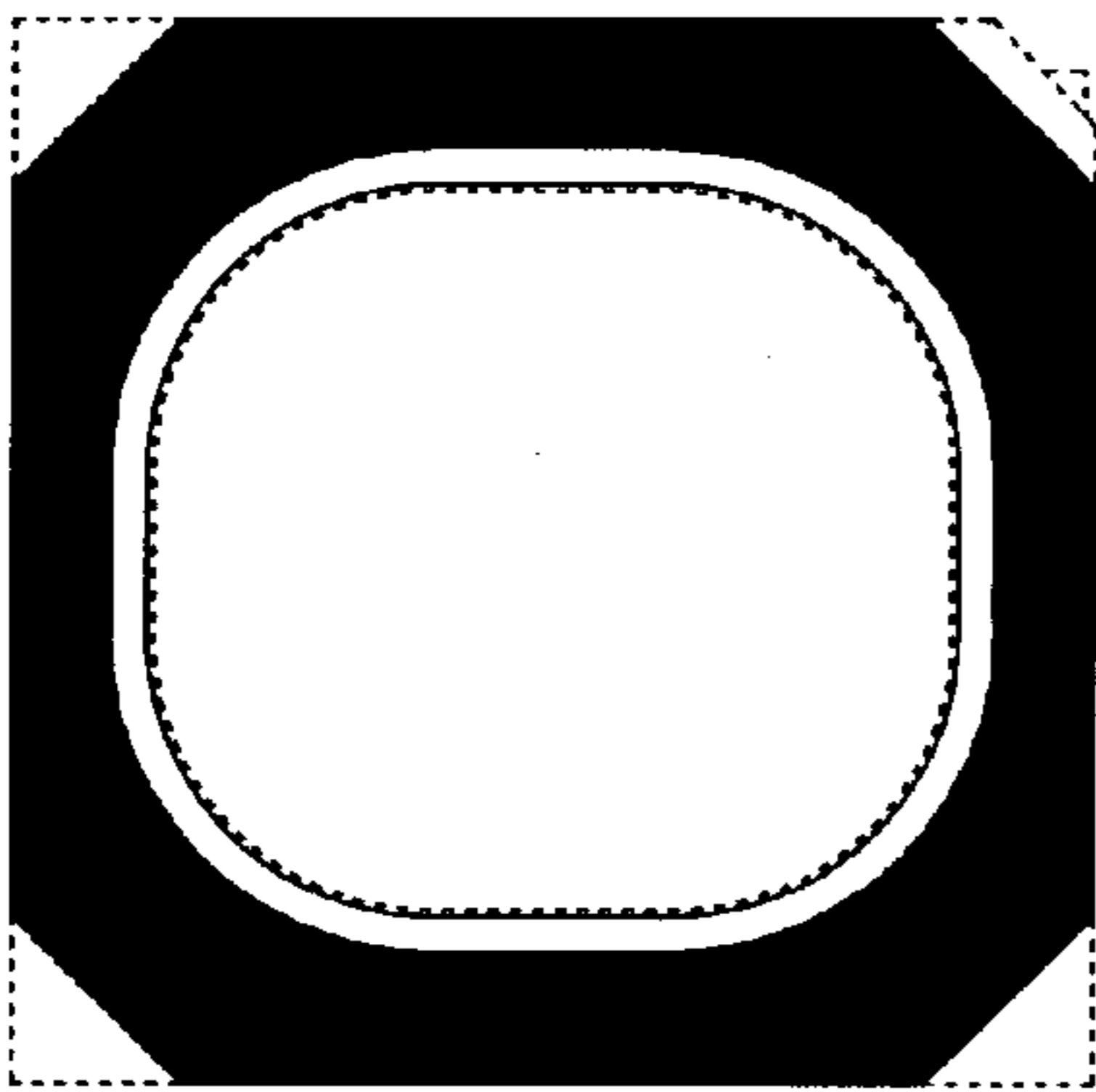


FIG. 4

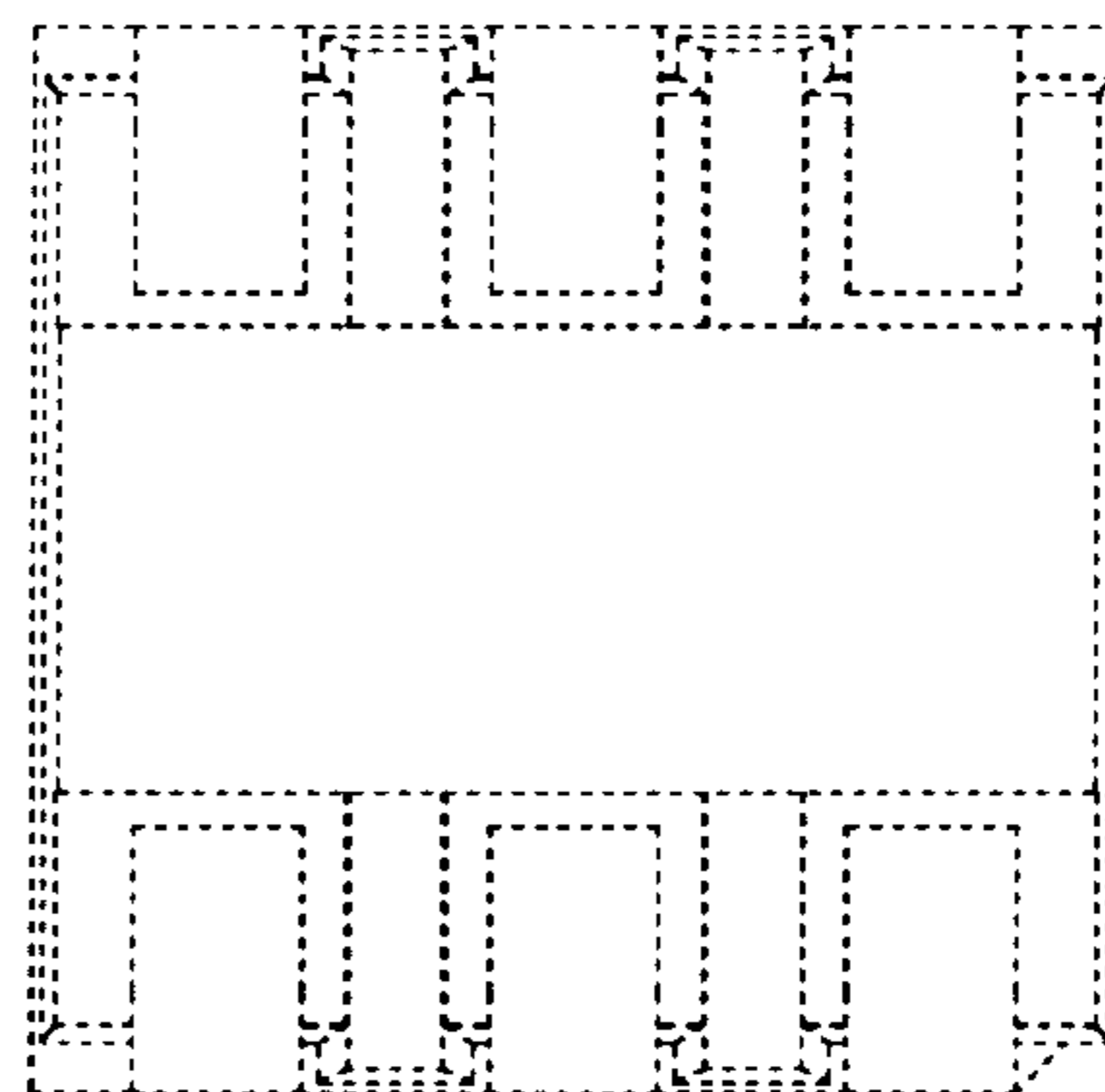


FIG. 5

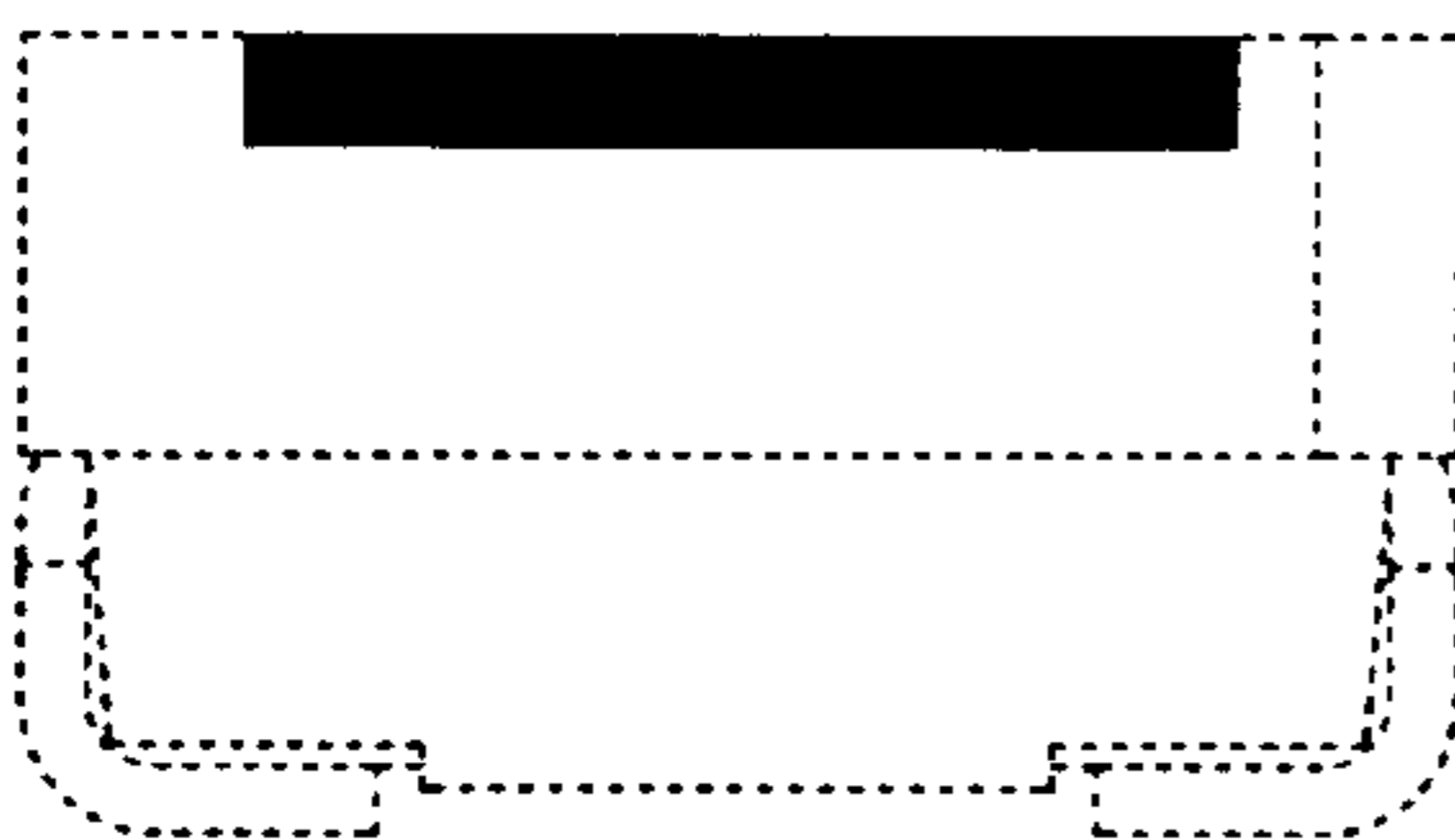


FIG. 6

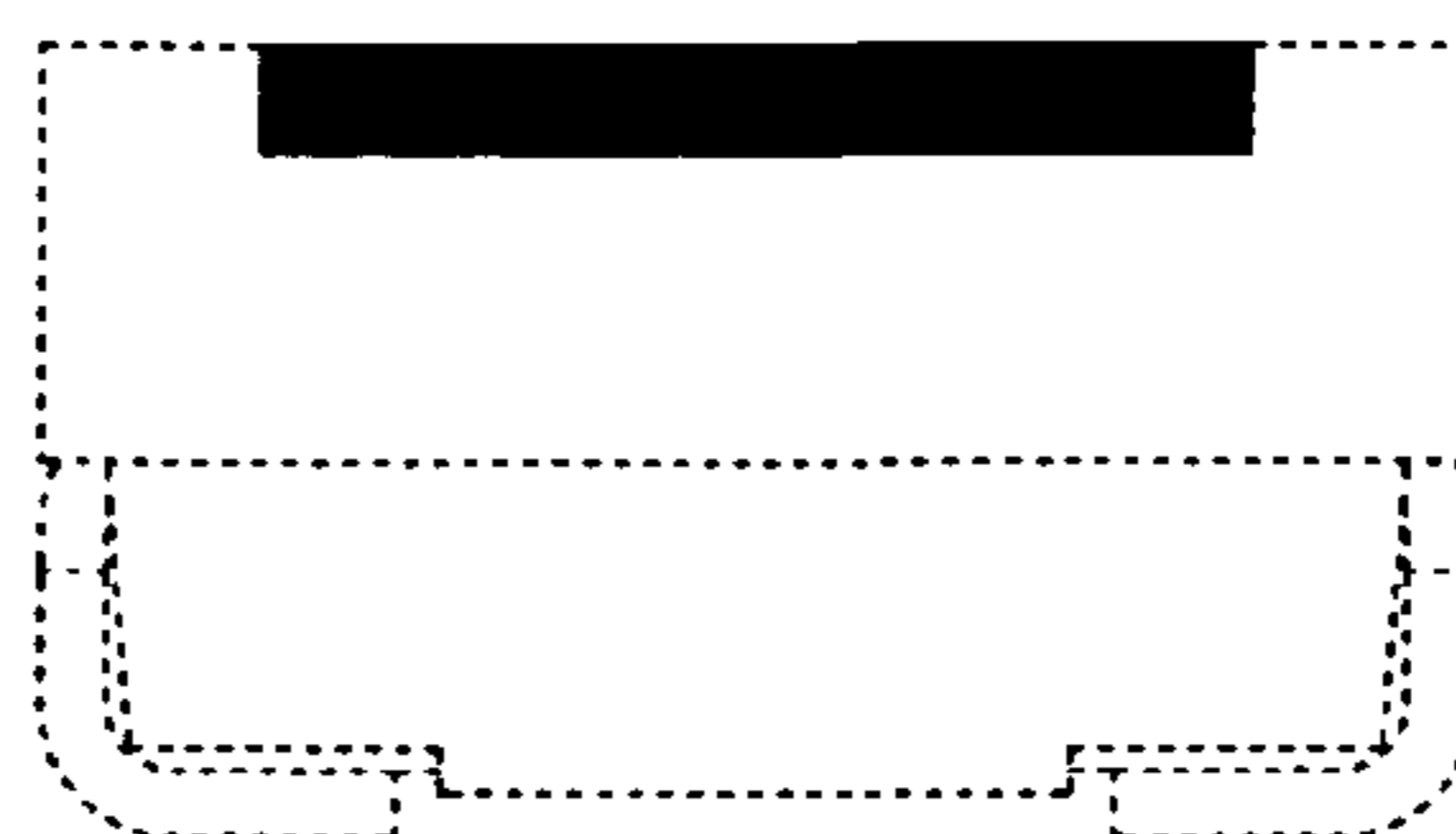


FIG. 7

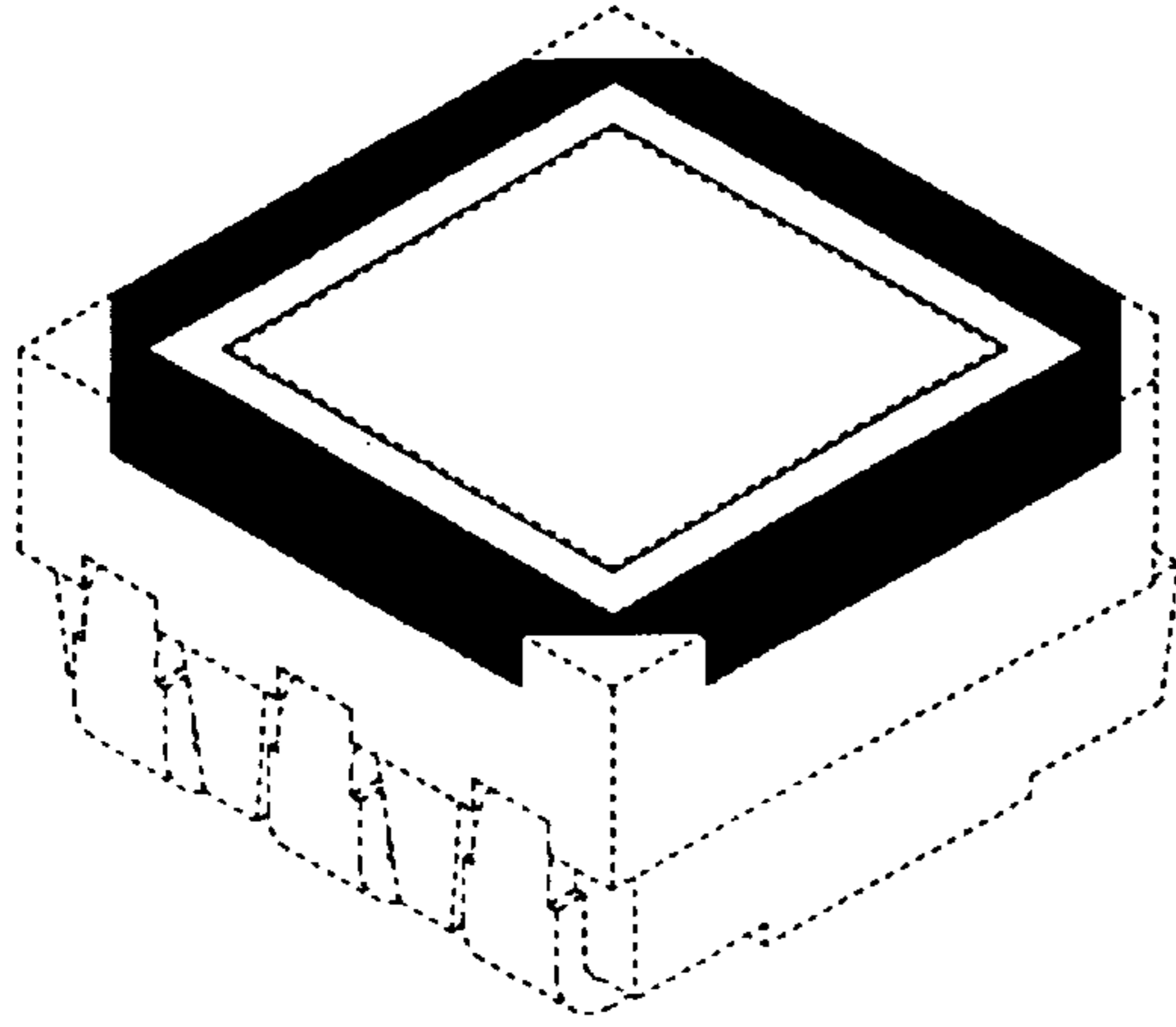


FIG. 8

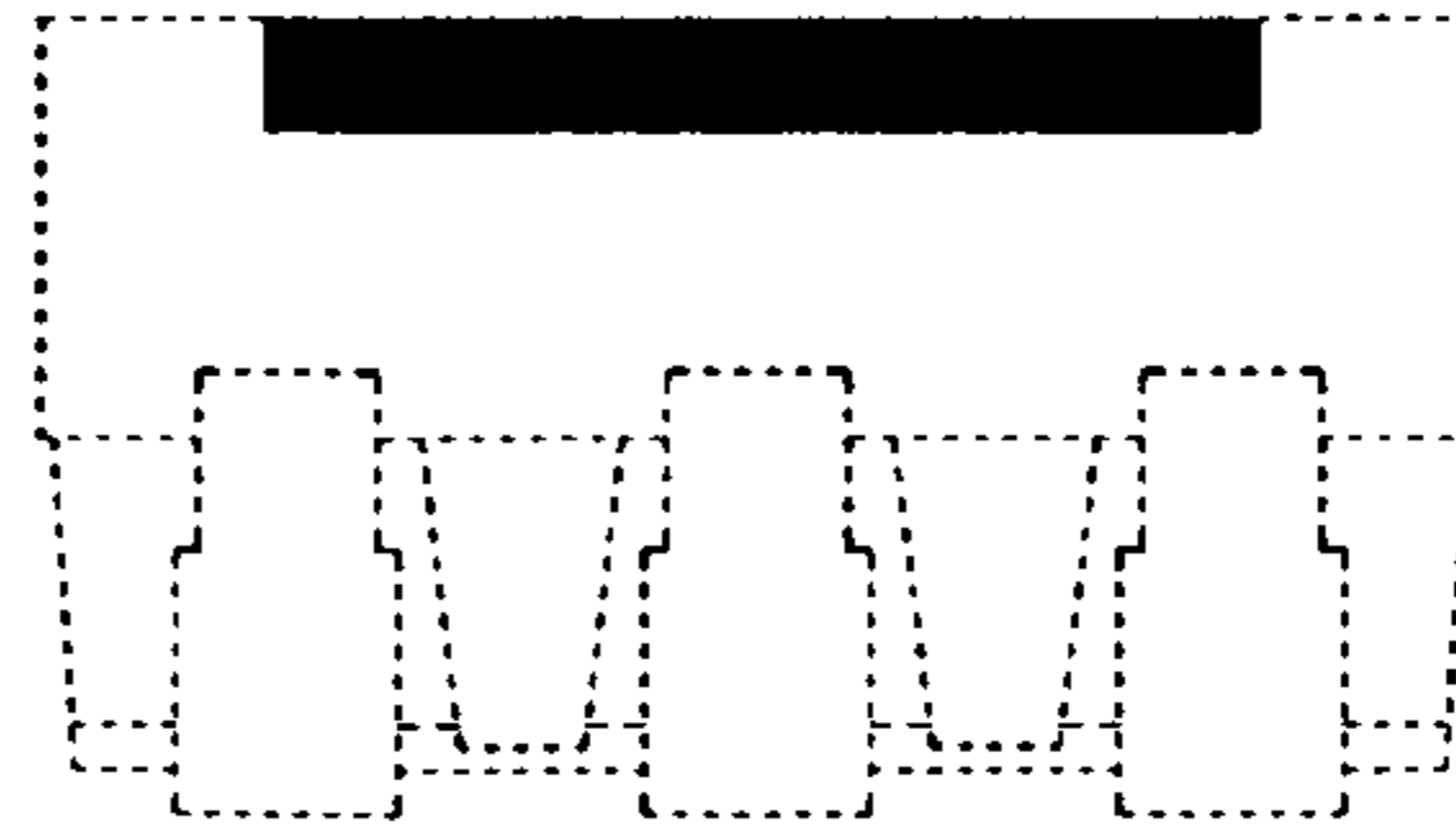


FIG. 9

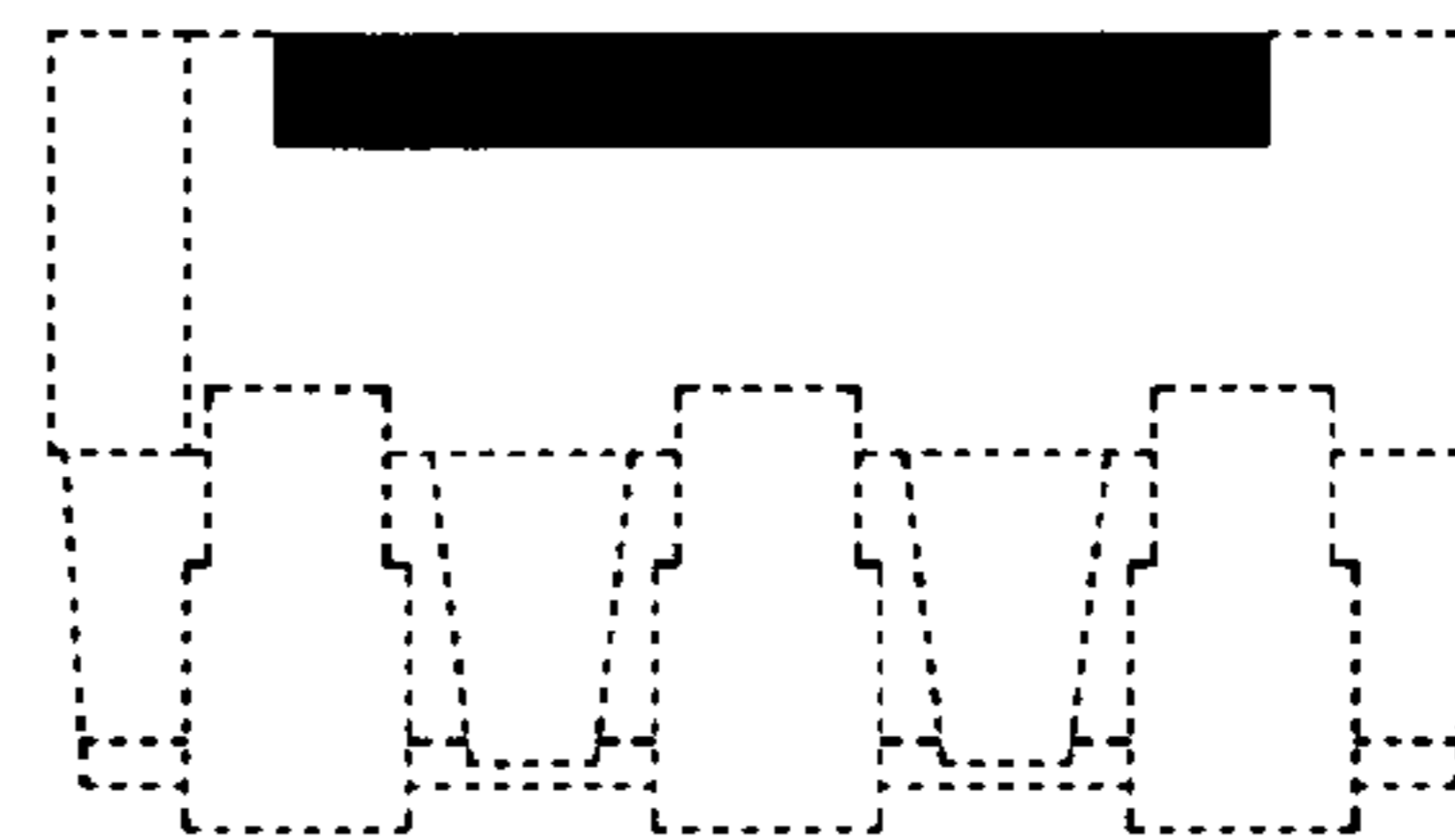


FIG. 10

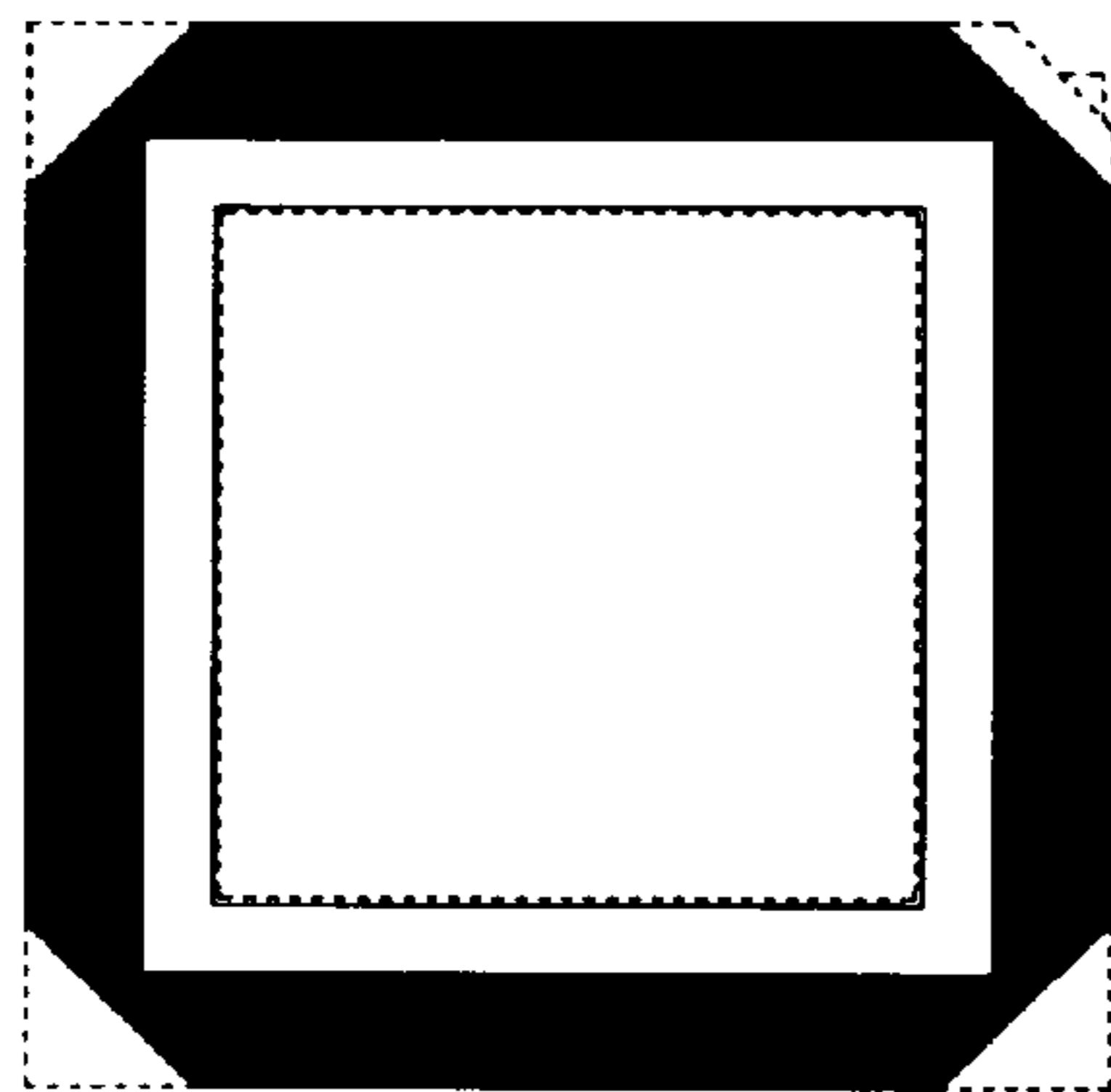


FIG. 11

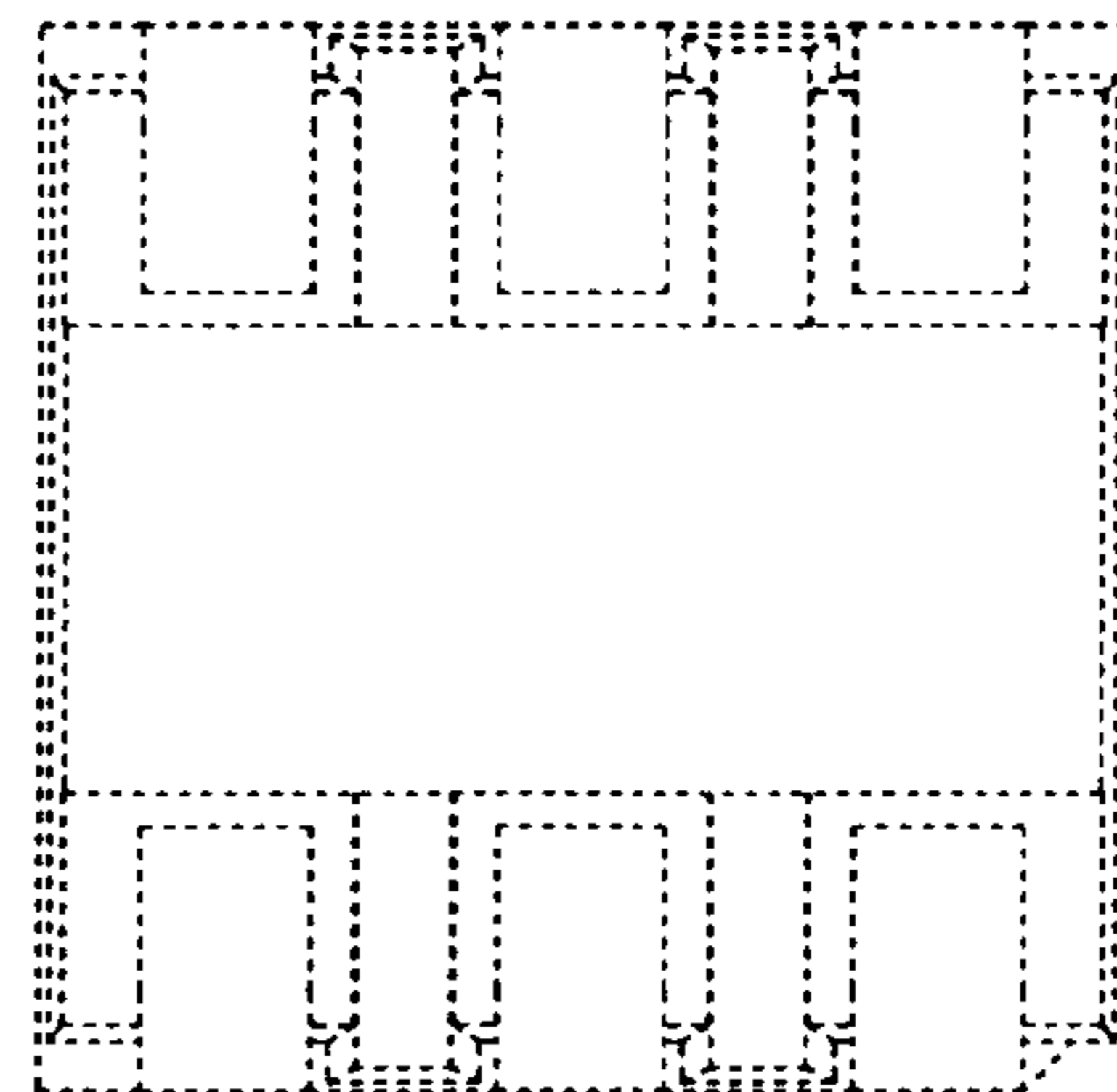


FIG. 12

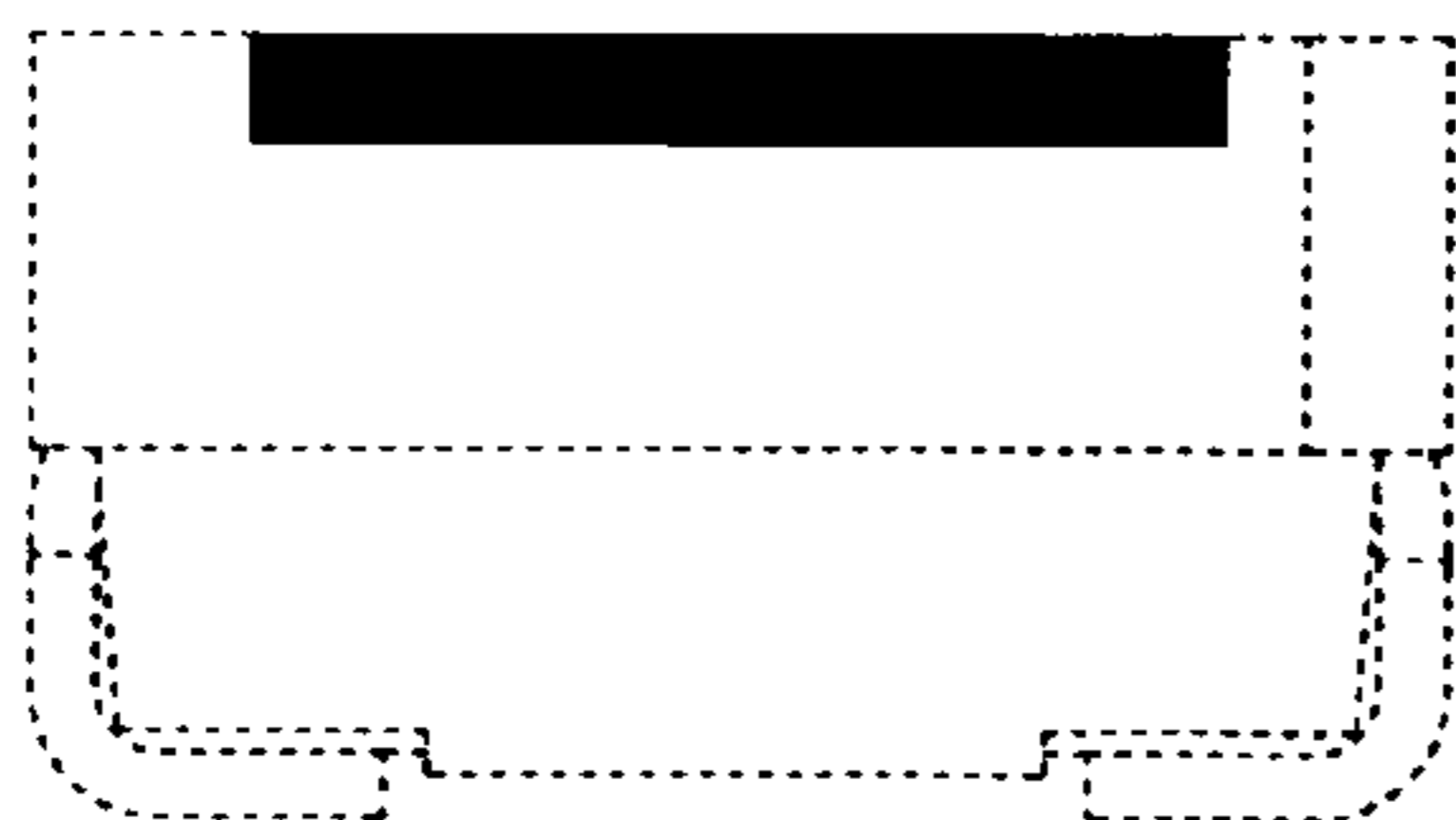


FIG. 13

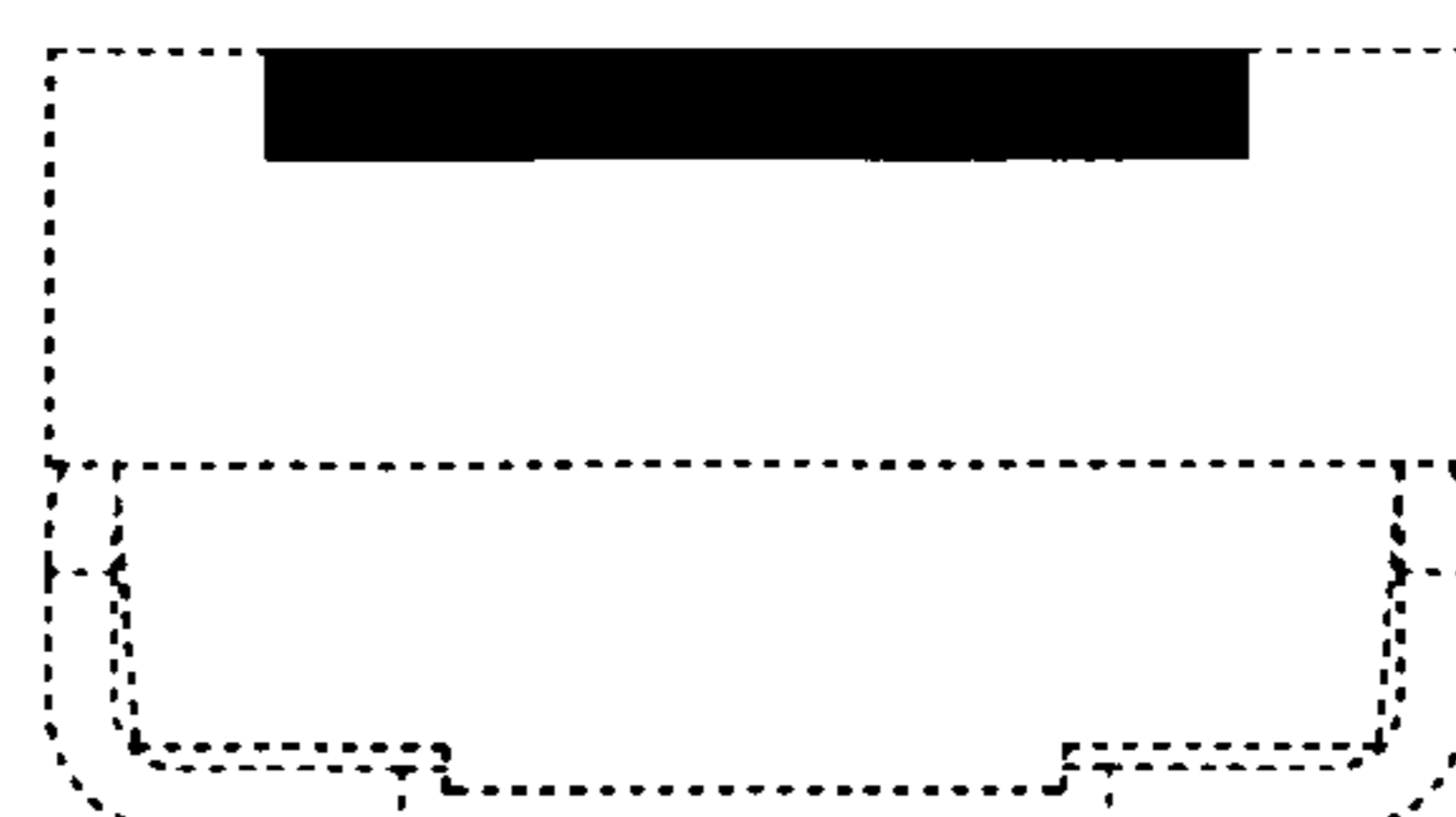


FIG. 14

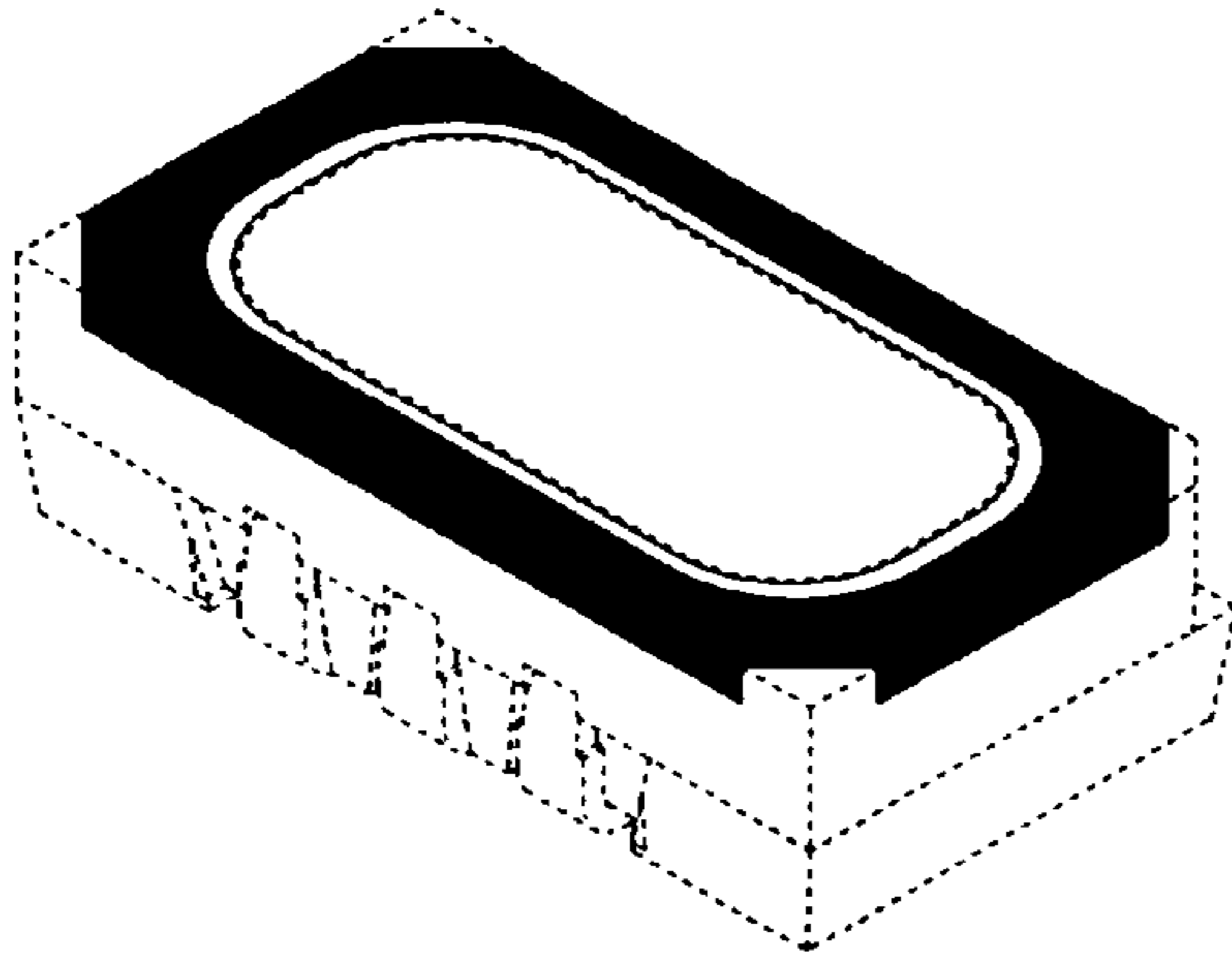


FIG. 15

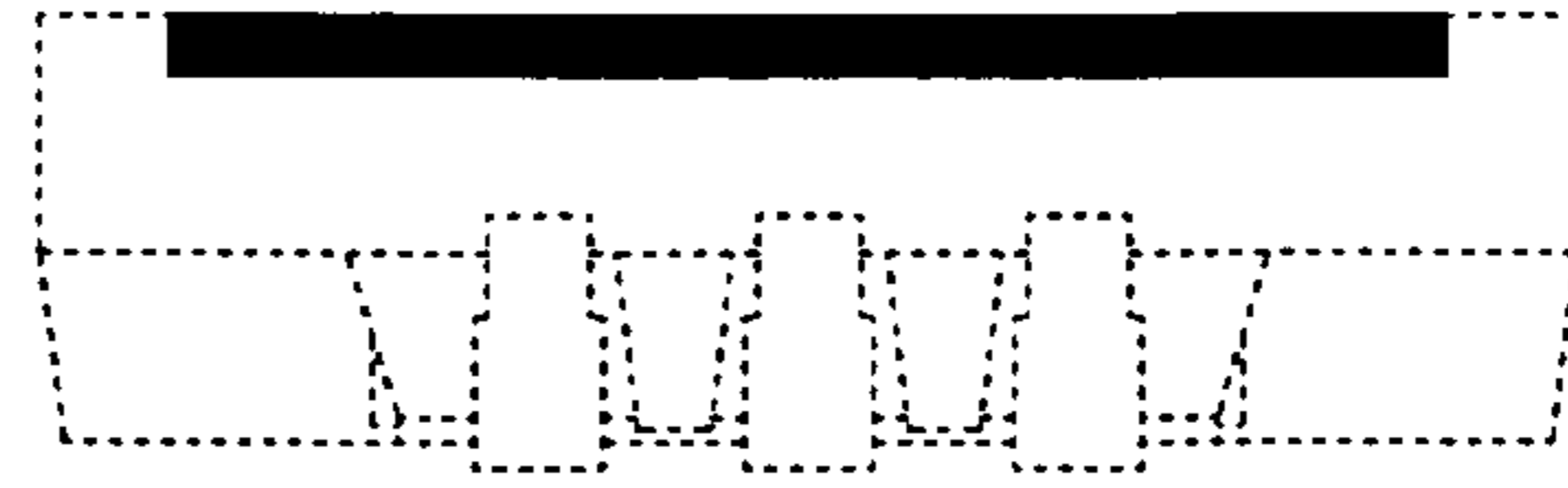


FIG. 16

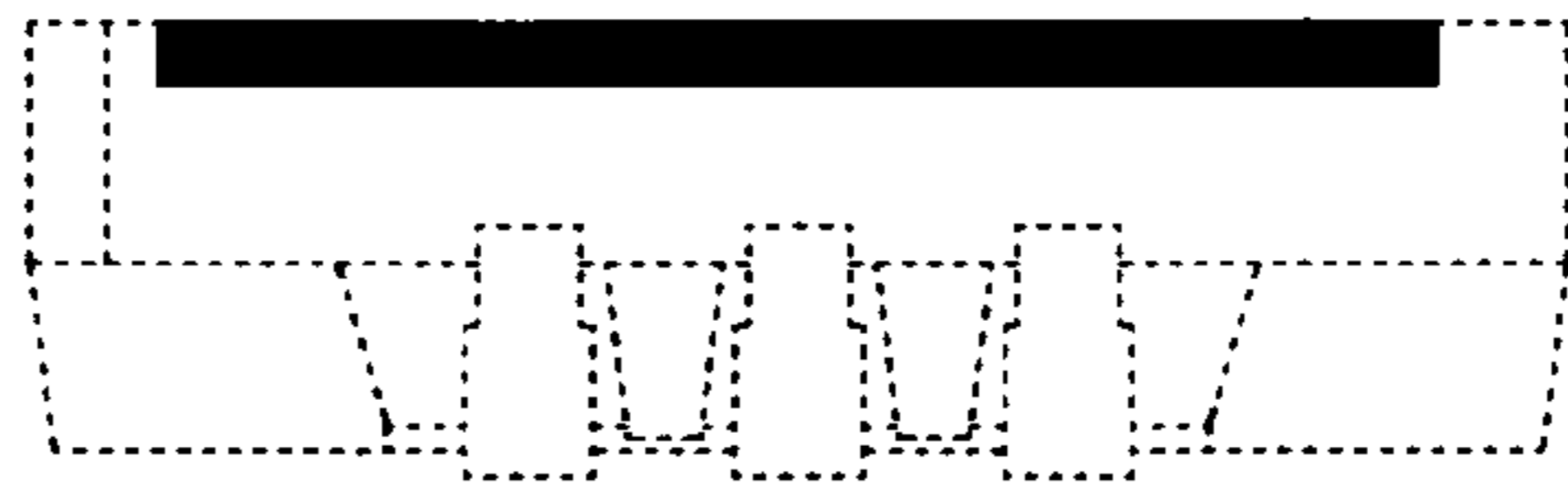


FIG. 17

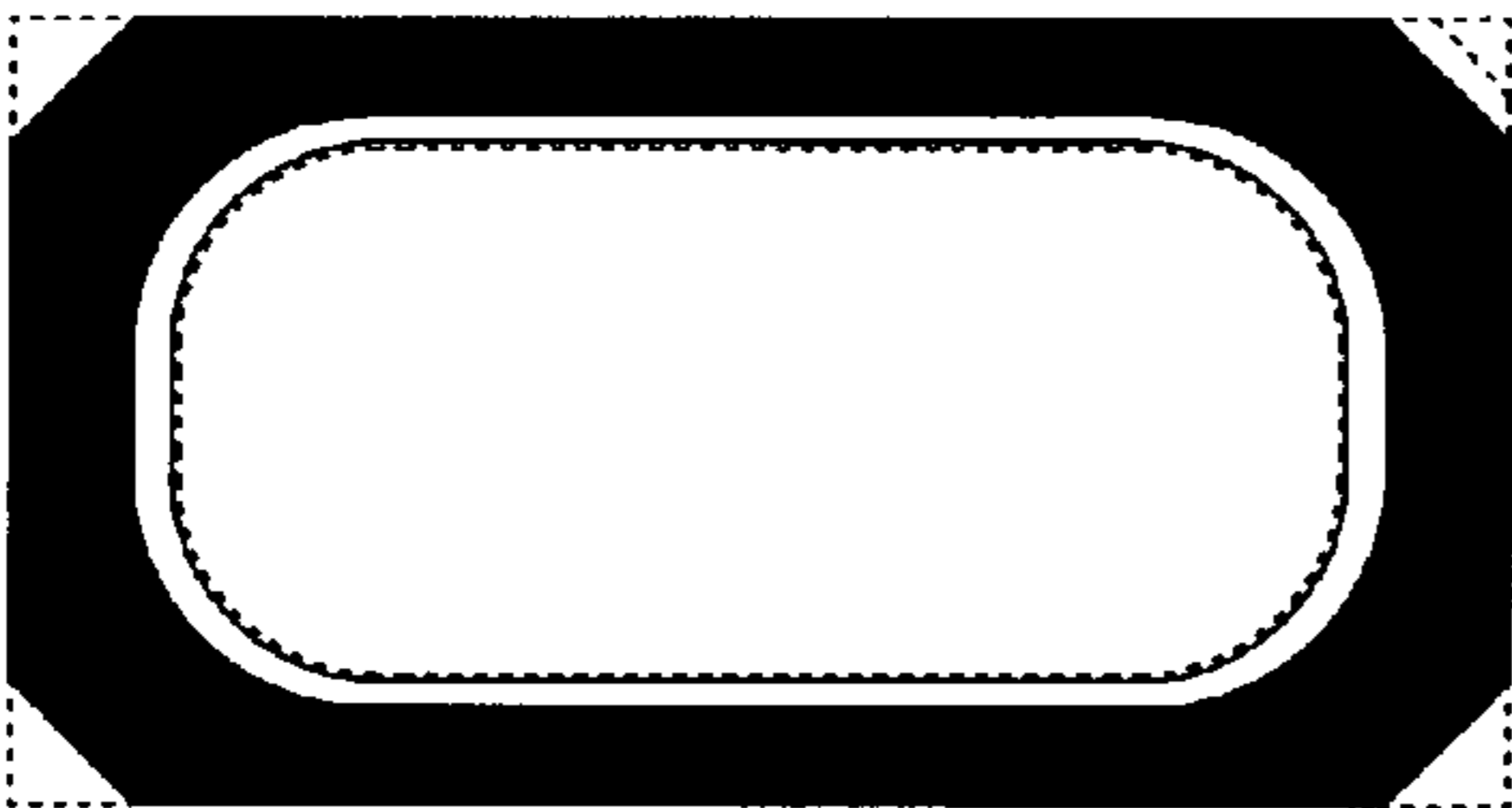


FIG. 18

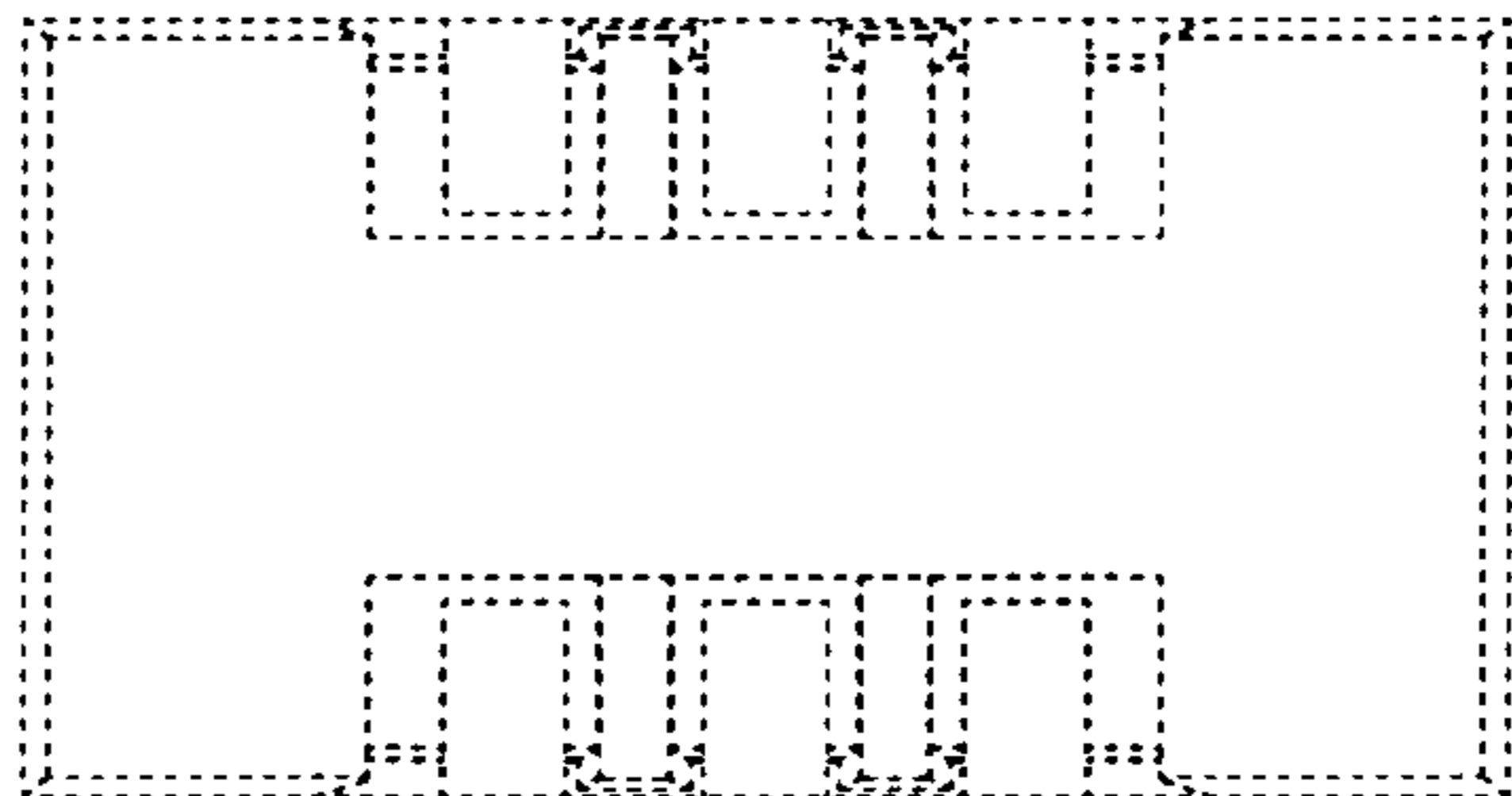


FIG. 19

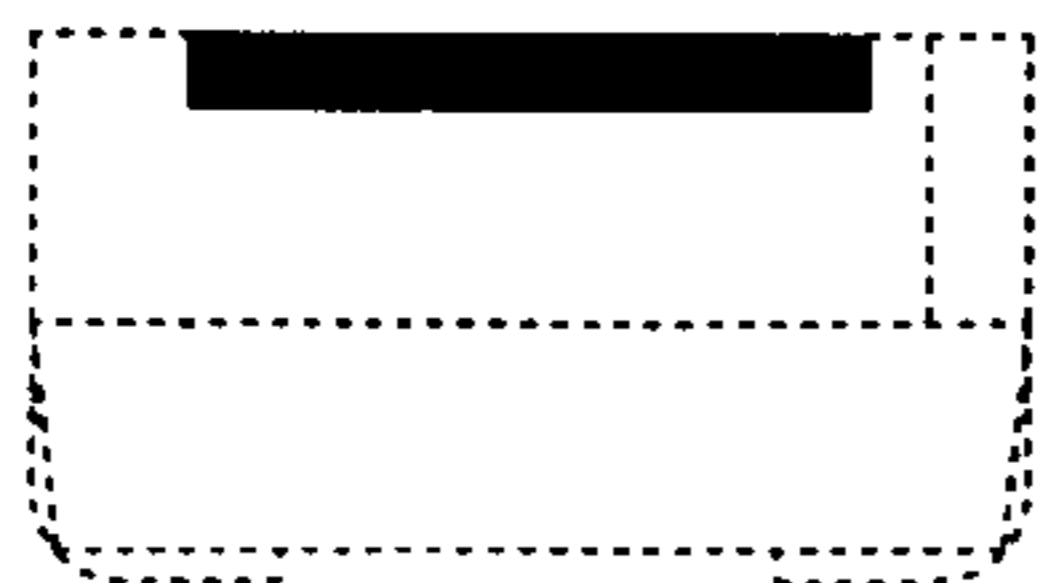


FIG. 20



FIG. 21